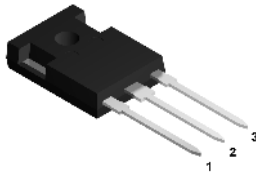
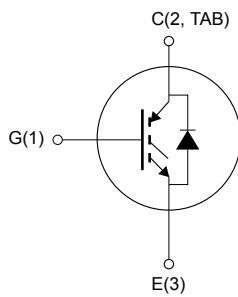


## Automotive-grade trench gate field-stop 600 V, 60 A very high speed V series IGBT featuring freewheeling SiC diode



TO-247 long leads



NG1E3C2T




### Product status link

[STGWA60V60DWFAG](#)

### Product summary

<b>Order code</b>	STGWA60V60DWFAG
<b>Marking</b>	G60V60DWFAG
<b>Package</b>	TO-247 long leads
<b>Packing</b>	Tube

### Features

- AEC-Q101 qualified 
- Maximum junction temperature:  $T_J = 175\text{ }^\circ\text{C}$
- $V_{CE(sat)} = 1.85\text{ V (typ.) @ } I_C = 60\text{ A}$
- Tail-less switching current
- Tight parameter distribution
- Low thermal resistance
- Positive  $V_{CE(sat)}$  temperature coefficient
- Silicon carbide diode with no-reverse recovery charge is co-packaged in freewheeling configuration

### Applications

- Automotive converters
- Totem-pole power factor correction

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the V series IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, the positive  $V_{CE(sat)}$  temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Co-packed with the IGBT a silicon carbide diode has been adopted: no recovery is shown at turn-off of the SiC diode and the already minimal capacitive turn-off behavior is independent of temperature. Its high forward surge capability ensures good robustness during transient phases.

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0\text{ V}$ )	600	V
$I_C$	Continuous collector current at $T_C = 25\text{ °C}$	80 <sup>(1)</sup>	A
	Continuous collector current at $T_C = 100\text{ °C}$	60	
$I_{CP}$ <sup>(1)</sup>	Pulsed collector current ( $t_p \leq 1\ \mu\text{s}$ , $T_J < 175\text{ °C}$ )	240	
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$I_F$	Continuous forward current at $T_C = 100\text{ °C}$	30	A
$I_{FRM}$ <sup>(1)</sup>	Repetitive peak forward current ( $T_C = 100\text{ °C}$ , $T_J = 175\text{ °C}$ , $\delta = 0.1$ )	125	
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ °C}$	375	W
$T_{STG}$	Storage temperature range	-55 to 150	°C
$T_J$	Operating junction temperature range	-55 to 175	°C

1. Limited by bonding wires.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case IGBT	0.4	°C/W
	Thermal resistance junction-case diode	0.9	
$R_{thJA}$	Thermal resistance junction-ambient	50	

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified

**Table 3. Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}, I_C = 2\text{ mA}$	600			
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 60\text{ A}$		1.85	2.3	V
		$V_{GE} = 15\text{ V}, I_C = 60\text{ A}, T_J = 125\text{ °C}$		2.15		
		$V_{GE} = 15\text{ V}, I_C = 60\text{ A}, T_J = 175\text{ °C}$		2.35		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1\text{ mA}$	5	6	7	
$V_F$	Forward on-voltage	$I_F = 30\text{ A}$		1.45	1.88	
		$I_F = 30\text{ A}, T_J = 125\text{ °C}$		1.7		
		$I_F = 30\text{ A}, T_J = 175\text{ °C}$		1.85		
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$			250	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 4. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}, f = 1\text{ MHz},$ $V_{GE} = 0\text{ V}$	-	8000	-	pF
$C_{oes}$	Output capacitance		-	280	-	
$C_{res}$	Reverse transfer capacitance		-	170	-	
$Q_g$	Total gate charge	$V_{CC} = 480\text{ V}, I_C = 60\text{ A},$ $V_{GE} = 0\text{ to }15\text{ V}$ (see Figure 28. Gate charge test circuit)	-	314	-	nC
$Q_{ge}$	Gate-emitter charge		-	48	-	
$Q_{gc}$	Gate-collector charge		-	142	-	

**Table 5. Switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}, I_C = 60\text{ A},$ $V_{GE} = 15\text{ V}, R_G = 4.7\text{ }\Omega$ (see Figure 27. Test circuit for inductive load switching)		35	-	ns
$t_r$	Current rise time			20	-	ns
$(di/dt)_{on}$	Turn-on current slope			2834	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time			190	-	ns
$t_f$	Current fall time			22	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			1.02	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			0.37	-	mJ
$E_{ts}$	Total switching energy			1.39	-	mJ

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 60\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 4.7\ \Omega$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 27. Test circuit for inductive load switching)		31	-	ns	
$t_r$	Current rise time			24	-	ns	
$(di/dt)_{on}$	Turn-on current slope				2263	-	A/ $\mu\text{s}$
$t_{d(off)}$	Turn-off delay time				228	-	ns
$t_f$	Current fall time				52	-	ns
$E_{on}^{(1)}$	Turn-on switching energy				0.99	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy				0.78	-	mJ
$E_{ts}$	Total switching energy				1.77	-	mJ

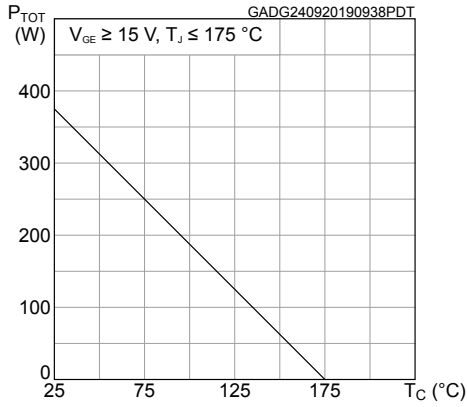
1. Including the reverse recovery of the SiC diode.
2. Including the tail of the collector current.

**Table 6. SiC diode switching characteristics (inductive load)**

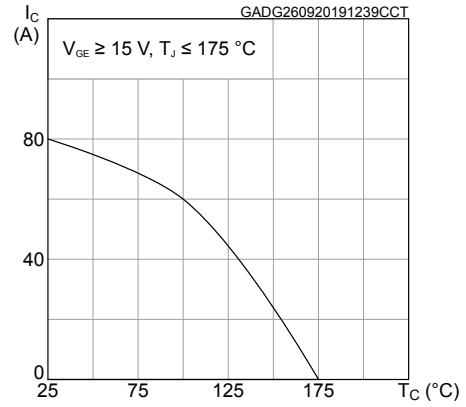
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$t_{rr}$	Reverse recovery time	$I_F = 60\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $dI_F/dt = 2570\text{ A}/\mu\text{s}$ (see Figure 27. Test circuit for inductive load switching)	-	200	-	ns	
$Q_{rr}$	Reverse recovery charge			-	282	-	nC
$I_{rrm}$	Reverse recovery current			-	8.5	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	30	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy			-	87	-	$\mu\text{J}$
$t_{rr}$	Reverse recovery time	$I_F = 60\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $dI_F/dt = 2570\text{ A}/\mu\text{s}$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 27. Test circuit for inductive load switching)	-	400	-	ns	
$Q_{rr}$	Reverse recovery charge			-	700	-	nC
$I_{rrm}$	Reverse recovery current			-	11	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	19	-	A/ $\mu\text{s}$
$E_{rr}$	Reverse recovery energy			-	225	-	$\mu\text{J}$

## 2.1 Electrical characteristics (curves)

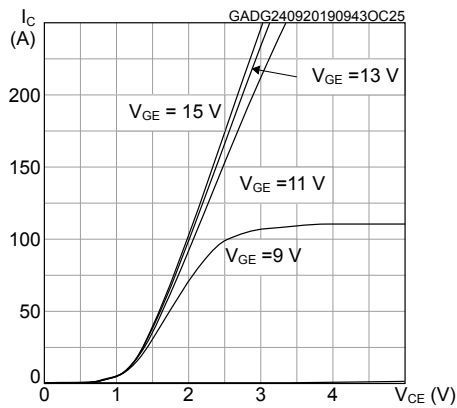
**Figure 1. Power dissipation vs case temperature**



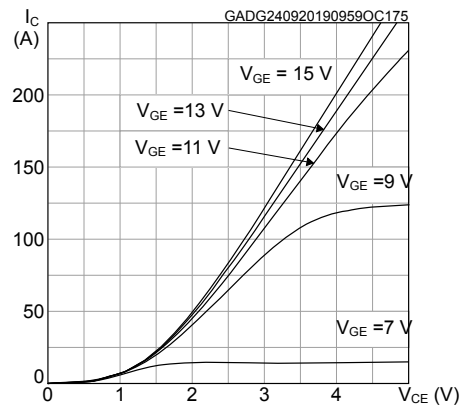
**Figure 2. Collector current vs case temperature**



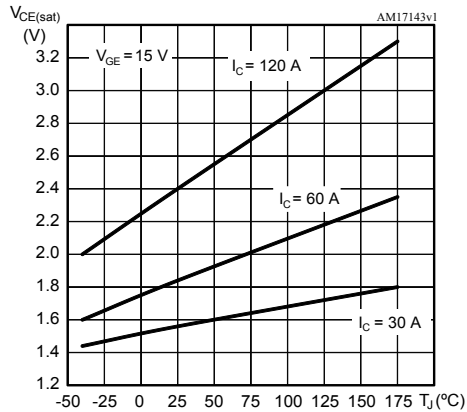
**Figure 3. Output characteristics (T<sub>J</sub> = 25 °C)**



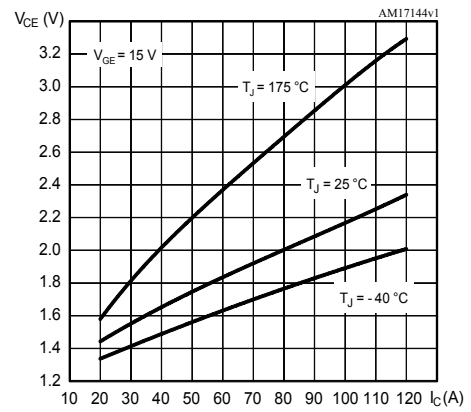
**Figure 4. Output characteristics (T<sub>J</sub> = 175 °C)**



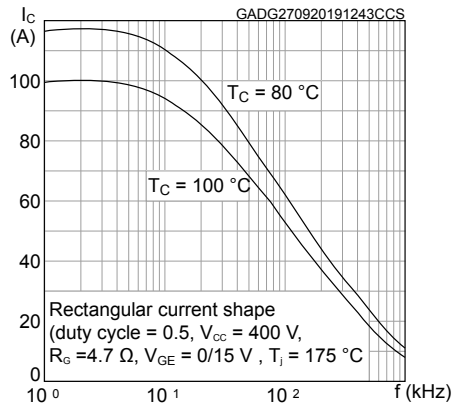
**Figure 5. V<sub>CE(sat)</sub> vs junction temperature**



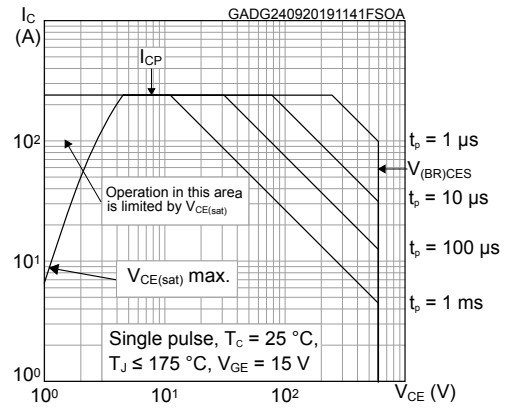
**Figure 6. V<sub>CE(sat)</sub> vs collector current**



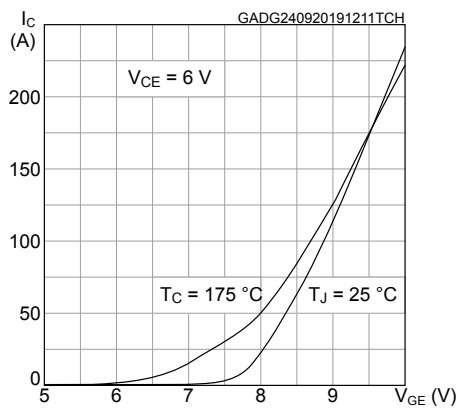
**Figure 7. Collector current vs. switching frequency**



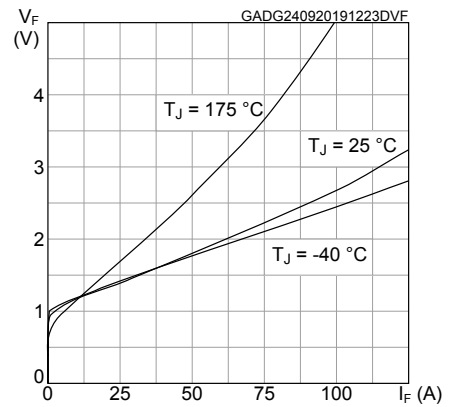
**Figure 8. Forward bias safe operating area**



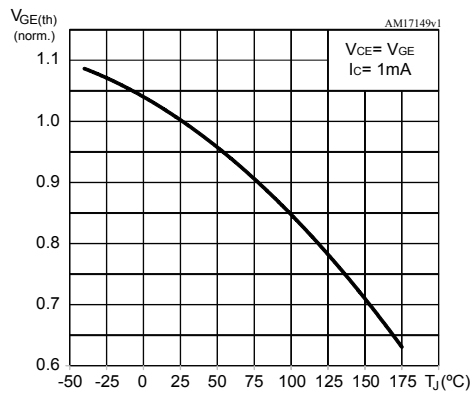
**Figure 9. Transfer characteristics**



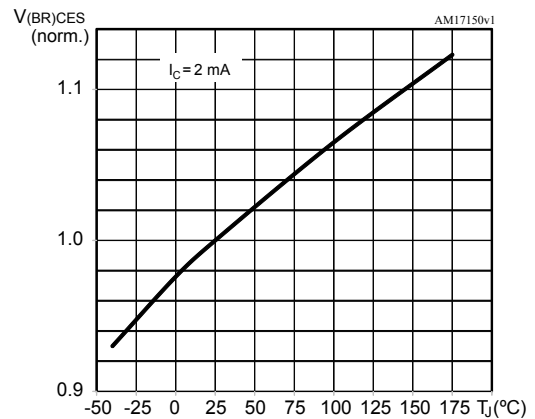
**Figure 10. Diode  $V_F$  vs forward current**



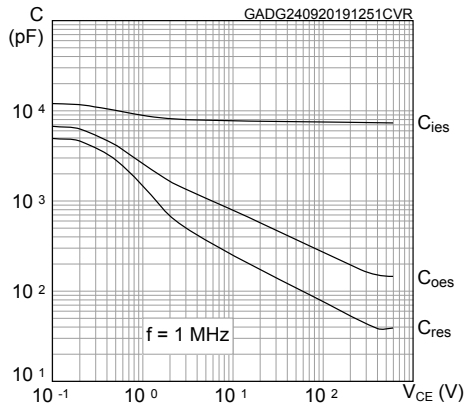
**Figure 11. Normalized  $V_{GE(th)}$  vs junction temperature**



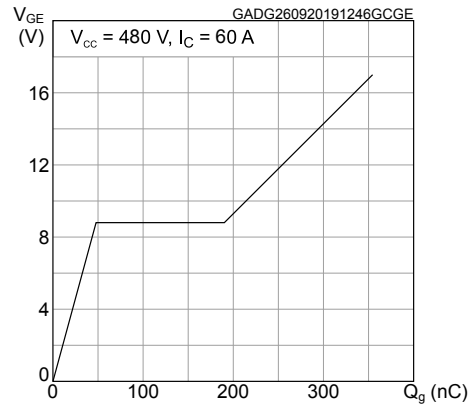
**Figure 12. Normalized  $V_{(BR)CES}$  vs junction temperature**



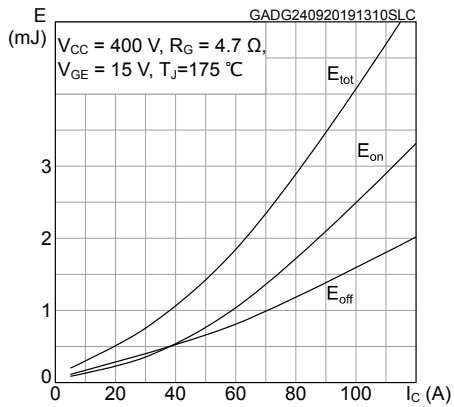
**Figure 13. Capacitance variations**



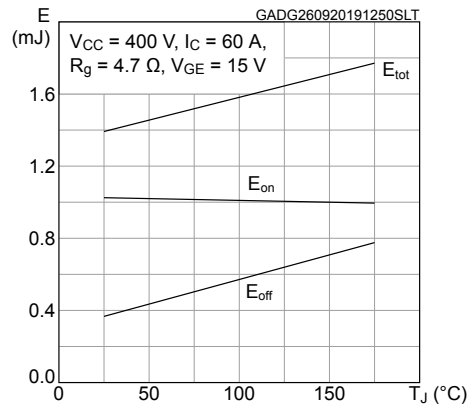
**Figure 14. Gate charge vs gate-emitter voltage**



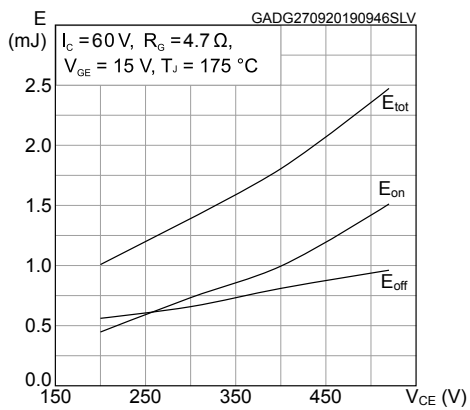
**Figure 15. Switching energy vs collector current**



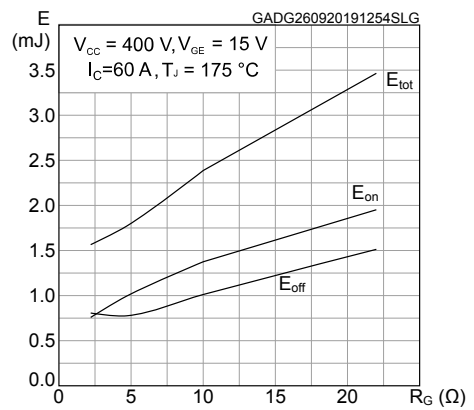
**Figure 16. Switching energy vs temperature**



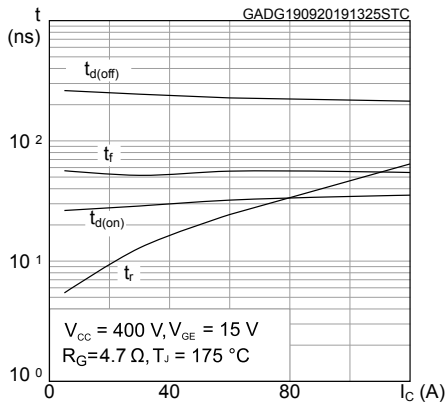
**Figure 17. Switching energy vs collector emitter voltage**



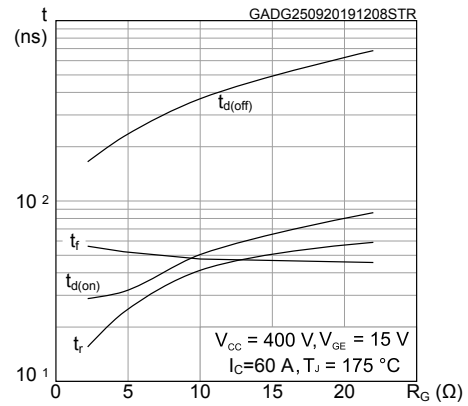
**Figure 18. Switching energy vs gate resistance**



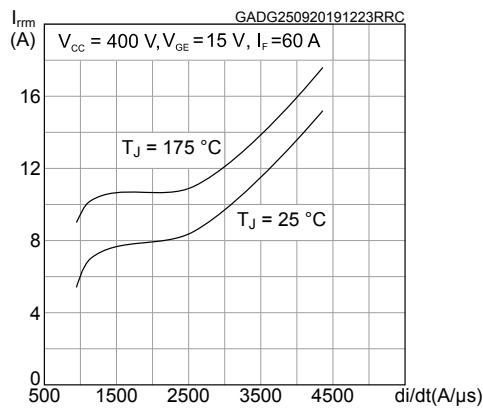
**Figure 19. Switching times vs collector current**



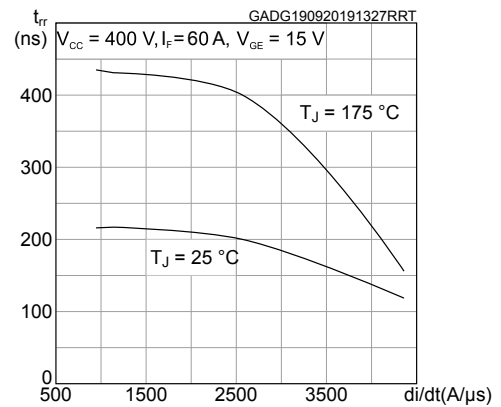
**Figure 20. Switching times vs gate resistance**



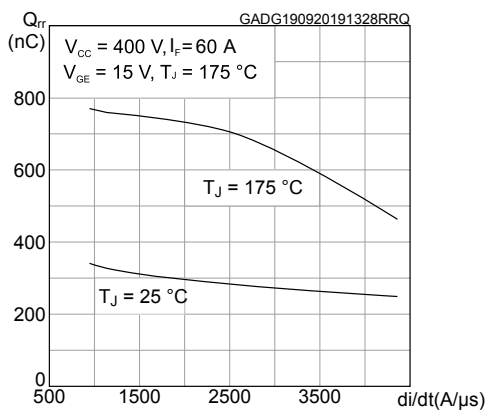
**Figure 21. Reverse recovery current vs diode current slope**



**Figure 22. Reverse recovery time vs diode current slope**



**Figure 23. Reverse recovery charge vs diode current slope**



**Figure 24. Reverse recovery energy vs diode current slope**

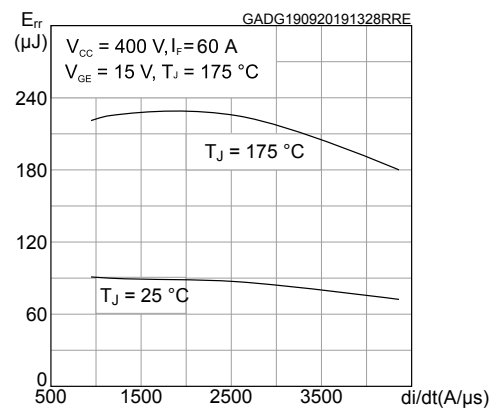




Figure 25. Thermal impedance for IGBT

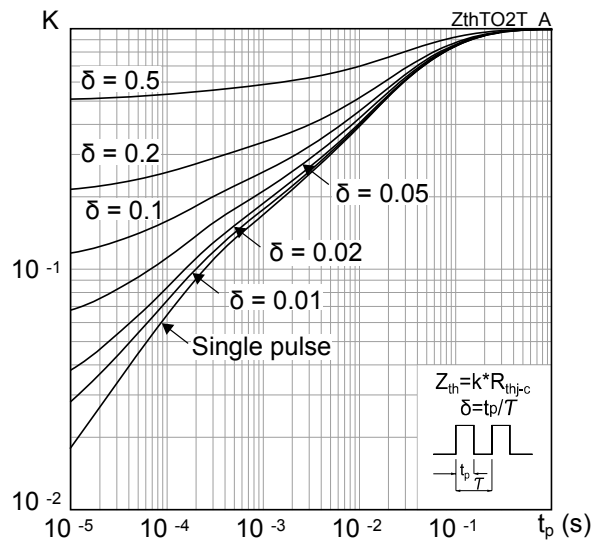
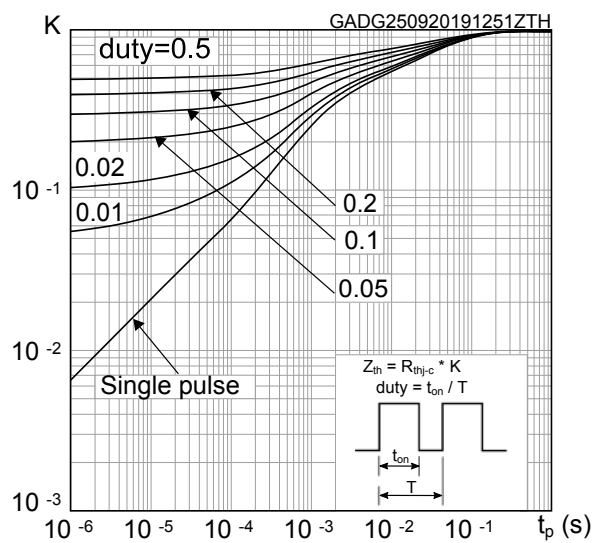
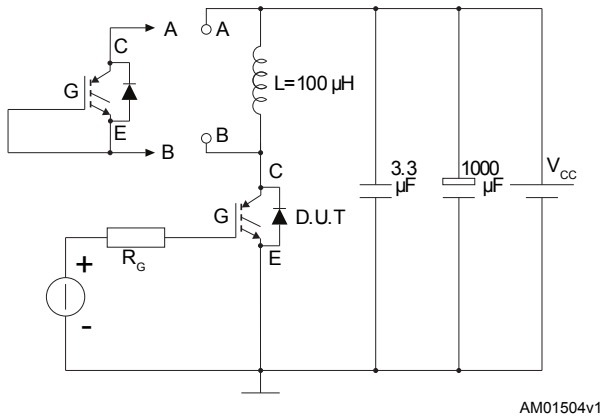
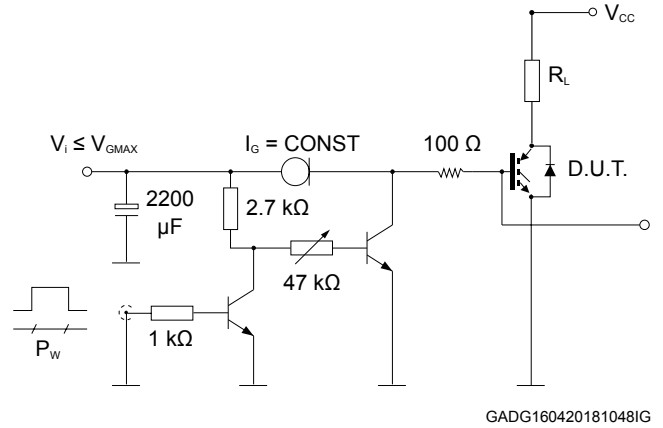
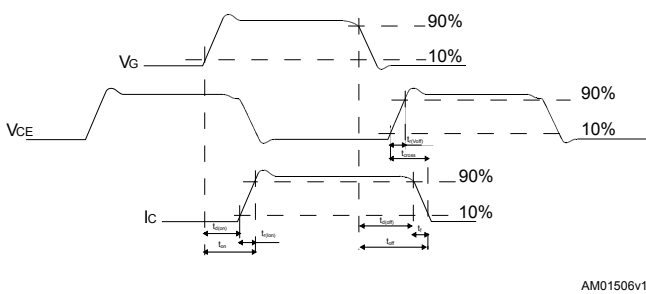
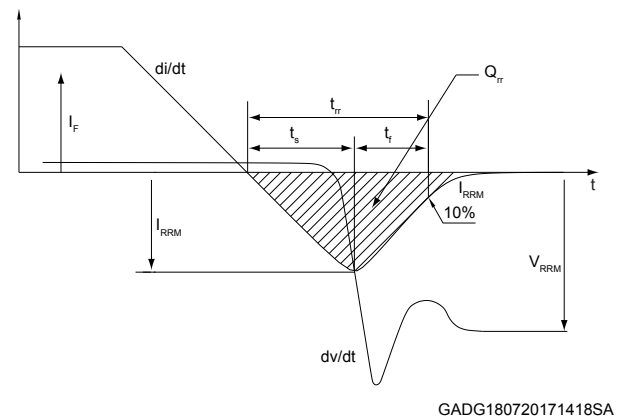


Figure 26. Thermal impedance for diode



### 3 Test circuits

**Figure 27. Test circuit for inductive load switching**

**Figure 28. Gate charge test circuit**

**Figure 29. Switching waveform**

**Figure 30. Diode reverse recovery waveform**


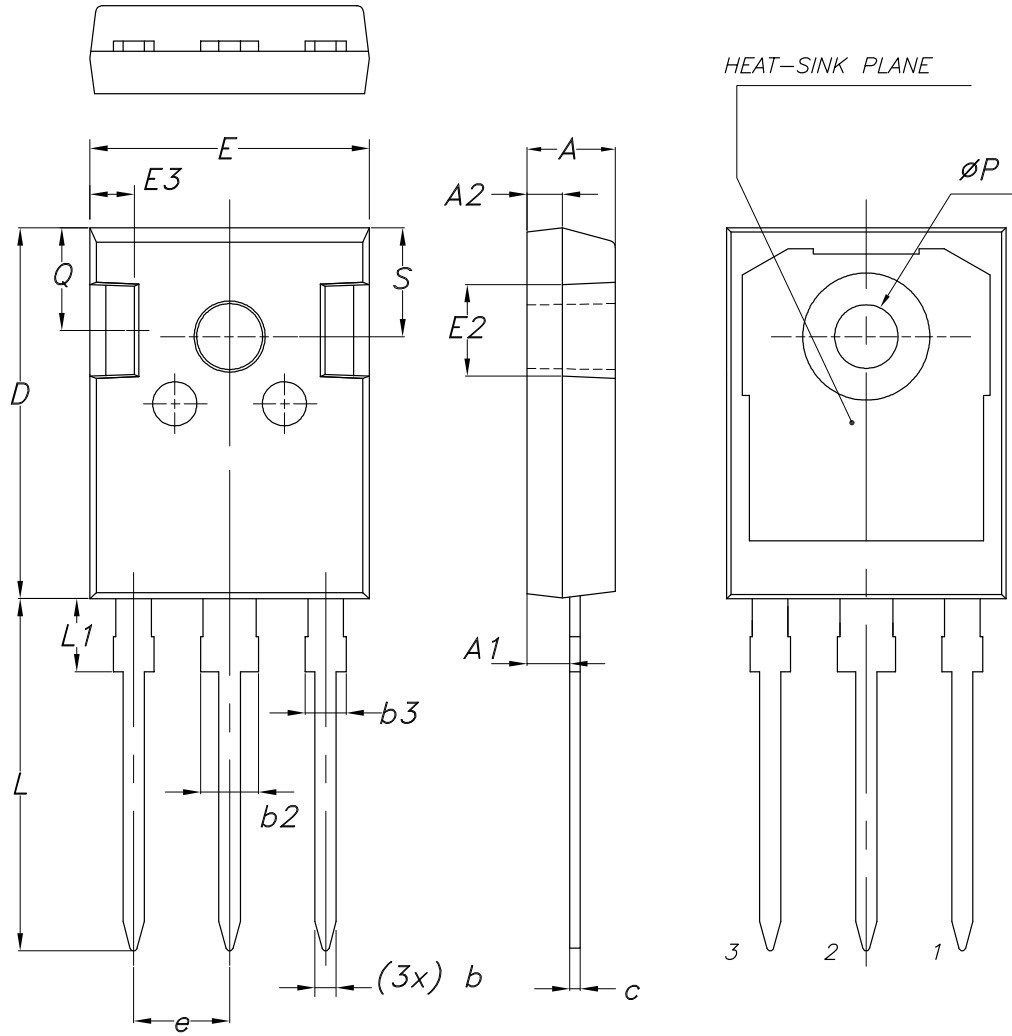
## **4 Package information**

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In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 long leads package information

Figure 31. TO-247 long leads package outline



8463846\_2\_F

**Table 7. TO-247 long leads package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

## Revision history

**Table 8. Document revision history**

Date	Version	Changes
01-Oct-2019	1	First release.
23-Oct-2019	2	Modified <a href="#">Table 3. Static characteristics</a> .

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